

FQU30N06L-VB Datasheet

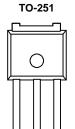
N-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)	Q _g (Typ.)			
60	$0.032 \text{ at V}_{GS} = 10 \text{ V}$	35 ^d	21.7			
00	0.037 at $V_{GS} = 4.5 \text{ V}$	30 ^d	21.7			

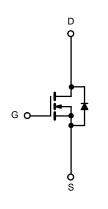
FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2002/95/EC





D Top View



N-Channel MOSFET

APPLICATIONS

- Power Supply
 - Secondary Synchronous Rectification
- DC/DC Converter

ABSOLUTE MAXIMUM RATINGS T _C = 25 °C, unless otherwise noted						
Parameter	Symbol	Limit	Unit			
Drain-Source Voltage		V _{DS}	60	V		
Gate-Source Voltage	V _{GS}	± 20				
Continuous Drain Current (T _J = 150 °C)	T _C = 25 °C	I _D	35 ^d	A		
	T _C = 70 °C	טי	30 ^d			
Pulsed Drain Current	I _{DM}	100	7			
Avalanche Current		I _{AS}			40	
Single Avalanche Energy ^a	L = 0.1 mH	E _{AS}	80	mJ		
Mariana Danca Diasia di ad	T _C = 25 °C	P _D	59.5 ^b	W		
Maximum Power Dissipation ^a	T _A = 25 °C ^c		2.7			
Operating Junction and Storage Temperature R	ange	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Limit	Unit		
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	46	°C/W		
Junction-to-Case (Drain)	R _{thJC}	2.1	- 'C/VV		

Notes:

- a. Duty cycle \leq 1 %.
- b. See SOA curve for voltage derating.c. When mounted on 1" square PCB (FR-4 material).
- d. Package limited.



SPECIFICATIONS $T_J = 25^{\circ}$	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	Зуппол	rest conditions	IVIIII.	тур.	IVIAA.	Offic	
	.,	V 0.V 1 050 A					
Drain-Source Breakdown Voltage	V _{DS}	$V_{DS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.0		3.5		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 250	nA	
		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$			50	μA	
		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 150 ^{\circ}\text{C}$			250		
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	50			Α	
Drain-Source On-State Resistance ^a	D	$V_{GS} = 10 \text{ V}, I_{D} = 12 \text{ A}$		0.032		0	
Diam-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$		0.037		Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 10 A		110		S	
Dynamic ^b							
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 30 V, f = 1 MHz		1100		pF	
Output Capacitance	C _{oss}			281			
Reverse Transfer Capacitance	C _{rss}			130			
Tatal Cata Chausa C	Q _g	V _{DS} = 30 V, V _{GS} = 10 V, I _D = 10 A		46		nC	
Total Gate Charge ^c				28			
Gate-Source Charge ^c	Q _{gs}	$V_{DS} = 30 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$		7			
Gate-Drain Charge ^c	Q _{gd}			6.7			
Gate Resistance	R _g	f = 1 MHz	0.4	2	4	Ω	
Turn-On Delay Time ^c	t _{d(on)}			8	16	ns	
Rise Time ^c	t _r	$V_{DD} = 30 \text{ V, R}_{1} = 1.5 \Omega$		9	18		
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_q = 1 \Omega$		35	53		
Fall Time ^c	t _f	Ç		9	18		
Drain-Source Body Diode Ratings ar		stics T _C = 25 °C ^b			-		
Continuous Current	I _S	T			50		
Pulsed Current	I _{SM}				100	Α	
Forward Voltage ^a	V _{SD}	I _F = 10 A, V _{GS} = 0 V		0.75	1.5	V	
Reverse Recovery Time	t _{rr}	·F .57.9.65 5 .		34	51	ns	
Peak Reverse Recovery Current		$I_{\rm F} = 10 \text{ A}, dI/dt = 100 A/\mu s$		2	3	A	
Reverse Recovery Charge	I _{RM(REC)}	1 _F = 10 Λ, αι/αι = 100 Λ/μδ		34	51	nC	

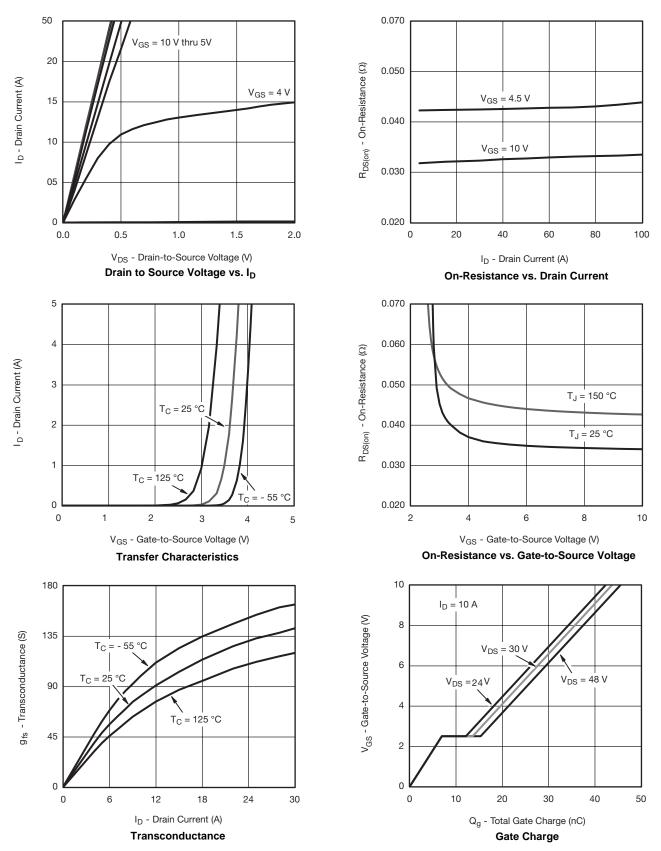
Notes:

- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

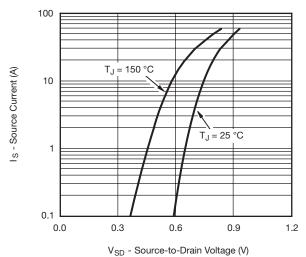


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

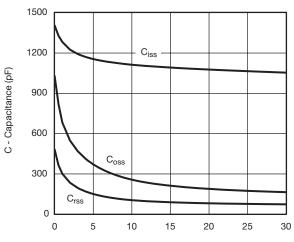




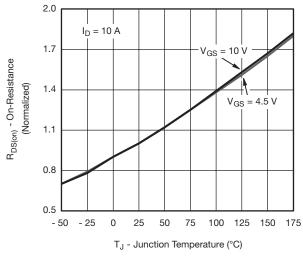
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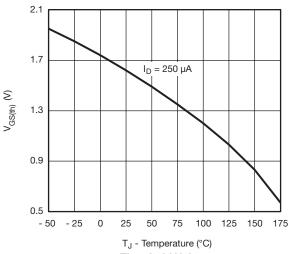
Source-Drain Diode Forward Voltage



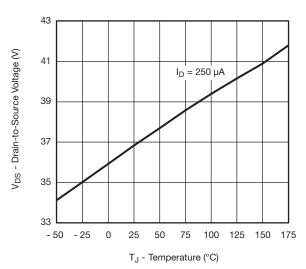
 V_{DS} - Drain-to-Source Voltage (V) $\label{eq:capacitance}$



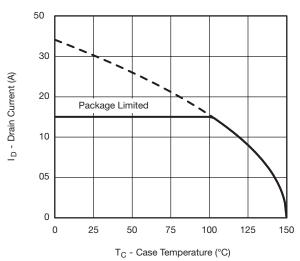
On-Resistance vs. Junction Temperature



Threshold Voltage



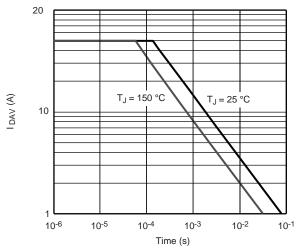
Drain Source Breakdown vs. Junction Temperature



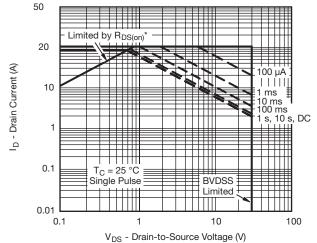
Current Derating



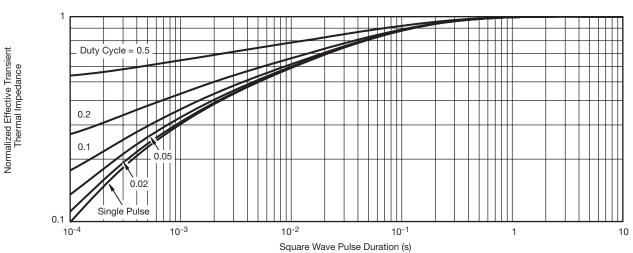
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Single Pulse Avalanche Current Capability vs. Time



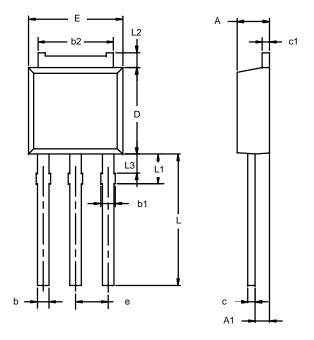
 * V $_{GS}$ > minimum V $_{GS}$ at which R $_{DS(on)}$ is specified **Safe Operating Area**



Normalized Thermal Transient Impedance, Junction-to-Case



TO-251AA (DPAK)



Note: Dimension L3 is for reference only.

	MILLIN	IETERS	INC	HES	
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
A1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
с1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
Е	6.48	6.73	0.255	0.265	
е	2.28 BSC		0.090 BSC		
L	8.89	9.53	0.350	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	
ECN: S-03946—Rev. E, 09-Jul-01 DWG: 5346					



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